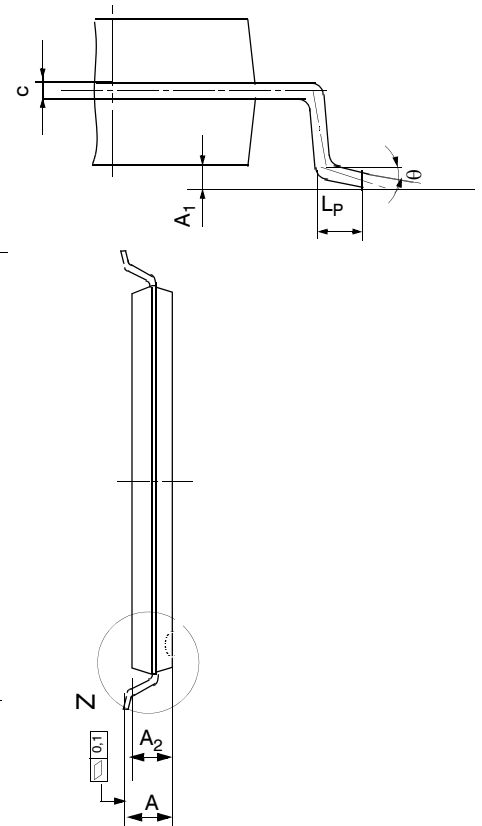
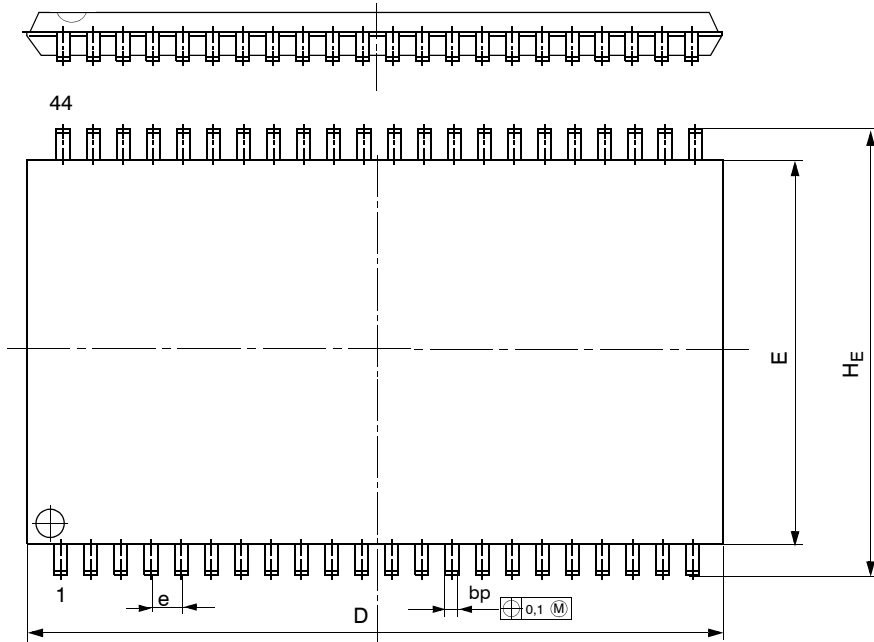



**Package TSOP (II) 44  
(400 mil)**
**MDS  
764**

Dimensions in millimetres

**Detail Z**

Based on JEDEC: JEP95 MO-133

**1 Dimensions**

Dimensions of Sub-Group B1	
$A_{max}$	1,20
$b_{Pmin}$	0,30
$b_{Pmax}$	0,45
$e_{nom}$	0,80
$H_{Emin}$	11,56
$H_{Emax}$	11,96
$L_{Pmin}$	0,40

Dimensions of Sub-Group C1	
$A_{min}$	—
$A_{1min}$	0,05
$A_{1max}$	0,15
$A_{2min}$	0,95
$A_{2max}$	1,05
$c_{min}$	0,12
$c_{max}$	0,21
$D_{min}^*$	18,28
$D_{max}^*$	18,54
$E_{min}^*$	10,03
$E_{max}^*$	10,29
$\theta_{min}$	0°
$\theta_{max}$	5°

- 2 Weight**  $\leq 0,3$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

\* without mold-flash

Zentrum Mikroelektronik Dresden AG		
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